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ICM-3216 Memory Board Specification

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WRITTEN BY: Ernesto Rey	DOCUMENT NUMBER	REV
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1. Introduction

The ICM-3216 Memory board contains the dynamic RAM for the ICM-3216 computer. The ICM-3216 is a complete computer system on two, double Eurocard size, printed circuit boards. All functions, such as CPU, memory, disk interface and I/O are contained on the ICM-3216 board set. The memory board will accept either 64K or 256K dynamic RAMs providing 1 to 4 megabytes of memory respectively. The system design will permit a maximum of two memory boards, each having the same RAM device types, to be installed at once. The other board is the CPU module which contains the NS32016 CPU cluster, boot EPROM, four serial interfaces, address mapping logic, SCSI interface, real-time clock, parallel printer interface and MiniBus interface. The CPU board is specified in document 426010289-000.

The ICM-3216 Memory board is designed to accept 150 nanosecond dynamic RAM devices and operate with a CPU board operating at 10 megahertz with no wait states for RAM access.

Features and Options

2.1. Features

The features of the ICM-3216 Memory board include:

- o 150 nanosecond RAM devices for 10 megahertz CPU board operation.
- 144 RAM devices organized with 18 bit wide data bus.
- Timing control for CAS and row / column addressing.
- o Control signal, address and data buffers.
- Address decoding.

2.2. Options

The following options will be selectable:

- o 64K or 256K RAM devices.
- o Selection of board 1 or board 2 in system.

3. Physical Description

The ICM-3216 Memory board is fabricated on a 11.020 inch by 9.180 inch printed circuit board (see Figure 1.)

Physical Characteristics:

Width:

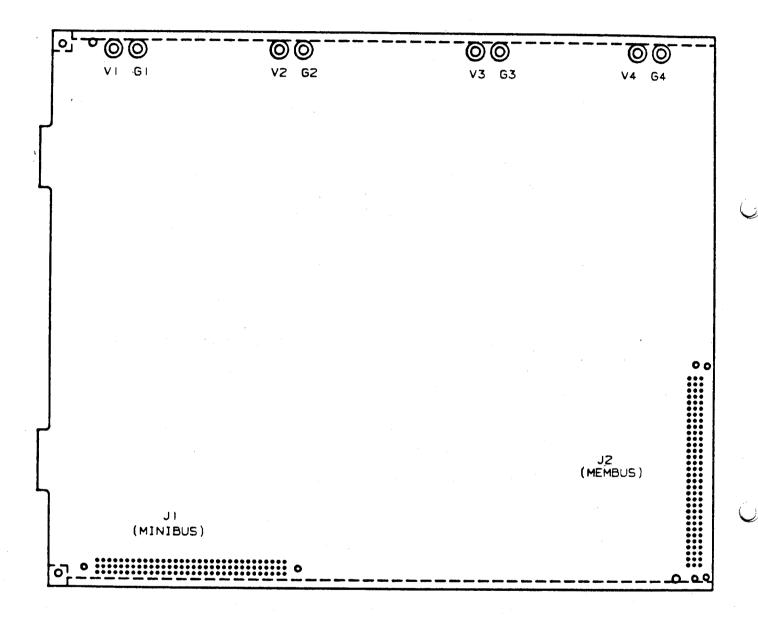
11.020 in. (28.0 cm.)

Height:

9.180 in. (23.3 cm.)

Depth:

0.80 in. (2.0 cm.)



ICM-3216 MEMORY BOARD

4. Interface Pin Signal Lists and Descriptions

4.1. MemBus Interface - J2

Connector J2 connects the Memory board to the CRU board. Pin assignments for connector J2 are specified in Table 4.1.

Me	mBus Connect	or Pinout	(J2)	
c01 - gn			a01 -	gnd
c02 - gn		gnd	a02 -	gnd
	IADOW b03 -	ND	a03 -	HLDD-RD
c04 - HA2		HA3~	a04 -	A23
c05 - HA0		+5V	a05 -	HA1~
c06 - gn		+5٧	a06 -	gnd
	IEML 607 -	gnd	a07 -	WRMEMH
c08 - gn	Y	gnd	a08 -	gnd
c09 - gn		CAST	a09 -	gnd
c10 - gn		+5٧	a10 -	gnd
c11 - REF	RESH~ b11 -	gnd	a11 -	gnd
c13 - RMA		RMA0	a12 -	gnd
		RMA2 +5V	a13 -	RMA3
c14 - gn		RMA5	a14 -	gnd RMA6
c16 - RMA		gnd	a16 -	RMA8
c17 - gn		AD00	a17 -	gnd
c18 - ADO		AD00	a18 -	AD03
c19 - ADO	1	gnd	a19 -	AD05
c20 - AD0		AD07	a20 -	AD08
c21 - gn		AD09	a21 -	gnd
c22 - AD1		AD11	a22 -	AD12
c23 - AD1		gnd	a23 -	AD14
c24 - AD1		RDDP1	a24 -	RDDP0
c25 - gn	id b25 -	WRDP1	a25 -	gnd
c26 - WRD		WRD00	a26 -	WRD01
c27 - WRD		gnd	a27 -	WRD03
c28 - WRD		WRD05	a28 -	WRD06
c29 - gn		WRD07	a29 -	gnd
c30 - WRD		WRD09	a30 -	WRD10
c31 - WRD		gnd	a31 -	WRD12
c32 - WRD		WRD14	a32 -	WRD15

Table 4.1

J2 - MemBus Pin Assignments

MNEMONIC	SIGNAL DESCRIPTION		
AD15 - AD00	Read Data, bits 15 through 00. Data word read from RAM.		
WRD15 - WRD00	Write Data, bits 15 through 00. Data word written to RAM.		
RMA8 - RMAO	RAM Address, bits 8 through 0. Represents RAM row address or column address. RMA8 is used only with 256K RAMs.		

RAST Row Address Strobe. Indicates RMA8 -RMA0 row address. CAST" Column Address Strobe. Indicates RMA8 RMA0 is column address. **WRMEMH** Write Memory High. Asserted when writing the high-order data byte to memory. WRMEML Write Memory Low. Asserted when writing the low-order data byte to memory. REFRESH~ Refresh, active-low signal. Asserted during a refresh cycle. **MSHADOW** Memory Shadow. Generated by CPU board; set upon power-up, cleared upon memory access with A23 = 1. When set, prevents RAM access, allowing CPU board EPROM to occupy low address space. High-Order Address. Represents CPU address bits 17 through 20 when using 64K RAMs; bits HAO~ - HA3~ 19 through 22 when using 128K RAMs. **A23** CPU Address 23. Must be low for RAM access. 64K~

64K~RAM. A jumper-set low level indicates that the memory board uses 64K RAMs; a high level indicates 256K RAMs.

RD~ Read. Asserted when reading data from memory.

HLDD_RD~ Hold Data Read. Extends read data valid beyond RD~.

RDDPO, RDDP1 Read Parity. Low-order byte and high-order byte parity bits read from memory.

WRDPO, WRDP1 Write Parity. Low-order byte and high-order byte parity bits written to memory.

4.2. MiniBus Interface - J1

J1 is a MiniBus connector but is used only for power connection and mechanical rigidity of the multiple board assembly. The pin signal list of the connections made to J1 are shown in Table 4.2.

=======================================		
MiniBus (Connector Pinout	(J1)
c01 - gnd	b01 -	a01 - gnd
c02 -	ь02 -	a02 -
c03 -	ь03 -	a03 -
c04 -	b04 -	a04 -
c05 -	b05 - gnd	a05 -
c06 - gnd	b06 - gnd	a06 - gnd
c07 -	b07 - +5V	a07 -
c08 -	b08 - +5V	a08 -
c09 -	609 - +5V	a09 -
c10 -	b10 - gnd	a10 -
c11 - gnd	b11 - gnd	a11 - gnd
c12	b12 - +5V	a12 -
c13 -	b13 - +5V	a13 -
c14 -	b14 - +5V	a14 -
c15 - c16 -	b15 -	a15 -
*	b16 - b17 -	a16 - a17 -
c17 - gnd c18 -		
	J	a18 - gnd a19 - gnd
c19 - gnd c20 -	b19 - gnd b20 - gnd	J
c21 - gnd	b20 grid b21 - gnd	a20 - gnd a21 - gnd
c22 -	b21 - grid	a21 gnd a22 gnd
c23 -	b23 -	a23 -
c24 -	b24 -	a24 -
c25 -	b25 -	a25 -
c26 -	b26 - +5V	a26 -
c27 - gnd	b27 - +5V	a27 - gnd
c28 -	b28 - gnd	a28 -
c29 -	b29 -	a29 -
c30 -	630 -	a30 -
c31 -	b31 -	a31 -
c32 - gnd	b32 -	a32 - gnd
	, =================================	

Table 4.2

J1 - MiniBus Pin Assignments

5. Environmental Requirements

Operating temperature: 0C to +55C

erating temperature. Oc to 133

Relative Humidity: to 90%, noncondensing

6. Power Requirements

Power requirements for the ICM-3216 Memory board are as follows:

Board	Voltage	Tolerance	Maximum Current (amp.)
1 MB with 64K RAMs 1 MB with 256K RAMs 2 MB	+5V DC +5V DC +5V DC	+/- 5% +/- 5% +/- 5%	1.5 1.1 1.2
4 MR	+5V DC	+/- 5%	1.5